Full Wafer & Singulated Die / Module Test System

Compact High Power Test and Reliability Verification Solution for Logic, Memory and Photonic Devices

SYSTEM BENEFITS

• Compact Flexible Solution for High Throughput Reliability Verification and Test
  ♦ Handles full wafer, panel, singulated die and module applications
  ♦ Identifies failing logic, memory and photonic die before final package integration
  ♦ High power thermal chuck dual Blade (slot) capability using WaferPak™ contactors or DiePak® carriers (for singulated die and modules)

• Cost-Effective Solution for High Power Wafer/Die/Module Verification and Test
  ♦ Configurable channel resources per Blade: Universal Channel Modules, High Voltage Channel Modules or High Current Channel Modules
  ♦ Up to 2,048 “Universal Channel” resources: (I/O, Clock, PPMU or DPS) per Blade with deep scan, pattern data and capture memory for testing of devices with BIST or DFT capabilities
  ♦ Up to 1,024 high voltage (29 V) or high current (2 A) sources resources per Blade

• Production Proven Full-Wafer Reliability Verification & Test Solution
  ♦ Reduces test costs by functionally testing wafers, die or modules during reliability verification
  ♦ Offers a total solution when configured with a WaferPak contactor, DiePak carrier, Wafer Aligner and DiePak Loader
  ♦ Protects devices with individual per channel over-current and over-voltage protection

“Setting the Test Standard for Tomorrow”